

Bill of Materials

TI DESIGNS
Part #:4679
Literature #:PMP

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	0.1uF	Capacitor, Ceramic, 100-V, X7R, 10%	1206	STD	Vishay
1	C2	47uF	Capacitor, Aluminum, 63V, 20%	8x10mm	EEVFK1J470P	Panasonic
1	C3	15pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C4	1800pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	C5	1uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	GRM32ER72A105KA01L	Murata
1	C6	0.22uF	Capacitor, Ceramic, 10V, X7R, 10%	0603	Std	Std
	C7	1uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	GRM32ER72A105KA01L	Murata
1	C8	0.22uF	Capacitor, Ceramic, 10V, X7R, 10%	0805	Std	Std
1	C9	1uF	Capacitor, Ceramic, 16-V, X7R, 10%	0805	GRM21BR71C105KA01L	Murata
3	C10	10uF	Capacitor, Ceramic, 16V, X5R, 10%	1210	C3225X5R1C106K	TDK
	C11	10uF	Capacitor, Ceramic, 16V, X5R, 10%	1210	C3225X5R1C106K	TDK
	C12	10uF	Capacitor, Ceramic, 16V, X5R, 10%	1210	C3225X5R1C106K	TDK
1	C13	0.1uF	Capacitor, Ceramic, 25-V, X7R, 10%	0603	Std	Vishay
1	D1	S1B	Diode, Rectifier, 1A, 100V	SMA	S1B	Diodes, Inc.
1	D2	SMAJ58A	Diode, TVS, 58V, 1W	SMA	SMAJ58A	Diodes Inc.
2	D3	HD01-T	Bridge Rectifier, 100V, 0.8A, Glass Passivated, SMD	MINI DIP4	HD01-T	Diodes, Inc
	D4	HD01-T	Bridge Rectifier, 100V, 0.8A, Glass Passivated, SMD	MINI DIP4	HD01-T	Diodes, Inc
2	D5	LN1271R	Diode, LED, Red, 20-mA, 0.9-mcd	0.068 x 0.049 inch	LN1271R	Panasonic
1	D6	MBRS1100TR	Diode, Schottky, 1-A, 100-V	SMB	STD	STD
	D7	LN1271R	Diode, LED, Red, 20-mA, 0.9-mcd	0.068 x 0.049 inch	LN1271R	Panasonic
2	J1	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	J2	0813-1X1T-57-F	Xfmr, MagJack, RJ-45, Single Port PoE	0.661 x 1.200 inch	0813-1X1T-57-F	Belfuse
1	J3	520252	Connector, Jack, Modular, 8 POS	0.705 x 0.820	520252	AMP
	J4	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	10uH	Inductor, SMT, 1.1A, 160milliohm	4.45x6.6mm	DO1608C-103	Coilcraft
1	L2	68uH	Inductor, SMT, 1.5A, 120-milliohm	0.472 sq inch	CDRH125NP-680MC	Sumida
1	Q1	Si2328	MOSFET, N-ch, 100-V, 1.5-A, 0.25-Ohms	SOT23	Si2328	Vishay
1	R1	178K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	24.9K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	357	Resistor, Chip, 1/4W, 1%	1206	Std	Vishay
1	R4	20K	Resistor, Chip, 1/10W, 5%	0805	Std	Std
1	R5	43K	Resistor, Chip, 1/16-W, 1%	0603	STD	Vishay
1	R6	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	0.39	Resistor, Chip, 1/4W, 1%	1206	WSL1206R1800FEA18	Vishay
1	R8	2K	Resistor, Chip, 1/10W, 5%	0805	Std	Std
1	R9	1.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	10.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	51.1	Resistor, Chip, 1/16W, 1%	0603	Std	Std
6	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone

COUNT	RefDes	Value	Description	Size	Part Number	MFR
6	TP2	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP3	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP4	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP6	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP7	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP8	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP9	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP10	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP11	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP12	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	1	U1	TPS23750PWP	IC, IEEE 802.3af Integrated Primary Side Controller	PWP20	TPS23750PWP

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